

PC96

Non Silicone Gap Filler

Description

PC96 is a yellowish white, highly filled tacky non silicone system suitable thermal dissipation of electronic devices. It has stable pot life and long shelf life even at room temperature of 25 °C.

Applications

Heat dissipation from electronic components.

Guidelines for Use

1. Wear rubber gloves when handling the product.
2. Pick up some of the product from the container using hand.
3. Peel off the liner. Place the product in required electronic part and circuit by hand.
4. Not require heating and curing.
5. The product can be applied and removed easily (care must be taken during installation to avoid tearing).

Properties

- REACH Compliant
- ROSH Compliant

Property	Typical Value	Unit	Test Method
Appearance	Yellowish White	-	Pen 10
Tackiness	Both Sides	-	-
Viscosity, Brookfield Cap 2000+, 25°C	Pad	cP	Pen 44
Operating temperature	-40 to 125	°C	Pen 92
Thermal Conductivity	2.5	W/mK	ISO/DIS 22007
Density	1.5	g/cm ³	Pen 14
Hardness	50	Shore 00	Pen 111

Packaging

Standard sheets

Customized shapes

Storage

Store this silicone thermal pad in air tight container, cool, dark place (temperature range from 20°C to 30°C) to prolong shelf life. Prevent moisture condition.

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